



Specifications

<i>Concept</i>	DC motor driven Z-linear-axis single-board-PC menu-controlled teach in, internal hard disk, operating and menu access via shuttle-wheel with push-button
<i>Wire types</i>	Gold- and aluminium wire 17,5...75 µm on 2" spool
<i>Bondhead</i>	Wire guide 45°/60° optional Contactless electronic touchdown-sensor US-Generator 65 or 100kHz reversible programmable 0 up to 5W Bond force 15 up to 300cN manually or electrically adjustable Clamp tear
<i>Display</i>	10,4" TFT Color-Display, 640x480 Pixel (VGA)
<i>Working Area</i>	Bondhead linear Z travel: 60 mm; step precision 1 µm <i>Programmable Y-Axis</i> 25 mm Standard workheight 70 mm 3 µm step resolution Manipulator in X and Y: 18x18 mm complies reduction 1:7
<i>Substrate</i>	Standard diameter 60 mm for components up to 2 x 2" 4 x 4" and 80 mm Ø optional, also with vacuum Digitally controlled heated stage, optional (Attention: 4x4" up to 200°C; 80mm up to 250°C)

5330

Manual Wire Bonder

The Wedge-Wedge-Bonder 5330 can process aluminium and gold wires from 17,5 to 75 µm. Due to the new designed clamp, it's possible to bond ribbons up to 125µm width. Due to the mechanical manipulator system the operator can create different kind of loops.

The bondhead is equipped with automatic feed- and tail-function, which allows optimal, user-friendly bonding.

The handling, supported by a colour display and the input with an shuttle-wheel make the programming of the machine very easy.

Due to the motor driven Z-axis you work always with repeatable results. Additionally every parameter can be saved to the internal harddisk.

Operators require only a minimum of training, making the 5330 the ideal choice for small scale production, laboratory, prototyping, pre-series and repair applications.

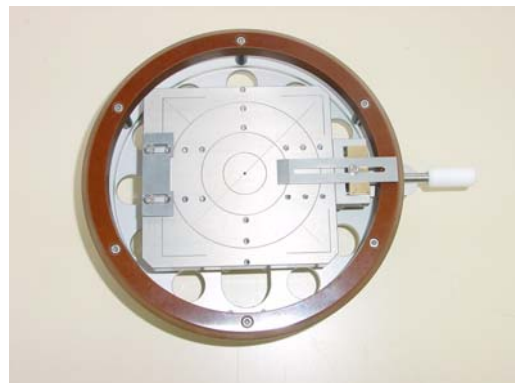
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<i>Control mode</i>	Manual, semi-auto Program line-step for testing via Shuttle-wheel
<i>Loop types</i>	triangle, rectangular, reverse, stitch, programmable
<i>Dimensions</i>	Height 400 mm, width 630 mm, depth 580 mm, weight approx. 30 kg
<i>Connections</i>	100...230 VAC, single-phase; if necessary air pres- sure / vacuum \varnothing 6 mm

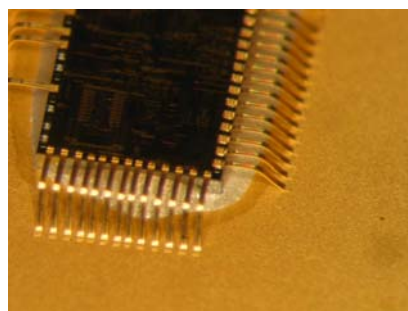
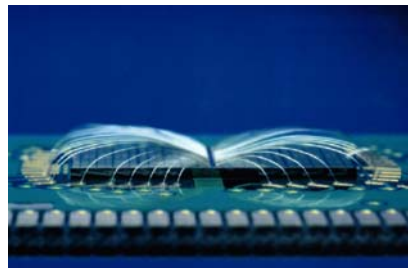
Workholder



Part No.: 5-0427-150-0
Workholder d=80mm
Un-/heated with Vacuum
+Adapter



optional
4-0402-210-0
Un-/heated
4x4" with mech. clamping a. Vacuum



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